

(C) WPI / DERWENT

AN - 1985-143838 [24]

AP - JP19830185594 19831004; JP19830185594 19831004; [Based on J60077999]

CPY - TANI

DC - M11 P23 P78

DR - 0235-U 1714-U

FS - CPI;GMPI

IC - A44C27/00 ; B44C1/00 ; C25F3/16

MC - M11-H02

PA - (TANI) TANAKA KIKINZOKU KOGYO KK

PN - JP60077999 A 19850502 DW198524 002pp

- JP5021998B B 19930326 DW199315 C25F3/00 002pp

PR - JP19830185594 19831004

XA - C1985-062578

XIC - A44C-027/00 ; B44C-001/00 ; C25F-003/16

XP - N1985-108428

AB - J60077999 Electrolytic polishing is effected by electrolysing in an aq. polishing bath contg. thiourea and sulphuric acid.

- Pref. concn. of thiourea is 5-200 g/l; and concn. of sulphuric acid is 1-100 ml/l. Electrolysis is pref. effected with alternating current, direct current, periodic reverse current or pulse current etc.

- USE/ADVANTAGE - Bright Au (alloy) surface with crystal grain structure pattern is produced. Suitable for surface finishing Au (alloy) ornaments such as rings, bracelets, pendants, watchcases, spectacle frames etc.(0/0)

AW - ALLOY

AKW - ALLOY

IW - ELECTROLYTIC POLISH GOLD ALLOY AQUEOUS BATH CONTAIN THIOUREA
SULPHURIC
ACIDIKW - ELECTROLYTIC POLISH GOLD ALLOY AQUEOUS BATH CONTAIN THIOUREA
SULPHURIC
ACID

NC - 001

OPD - 1983-10-04

ORD - 1985-05-02

PAW - (TANI) TANAKA KIKINZOKU KOGYO KK

TI - Electrolytic polishing of gold (alloy) - using aq. bath contg.
thiourea and sulphuric acid